



100V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET POWERDI5060-8

Product Summary

BVDSS	R _{DS(ON)} Max	I _D T _C = +25°C (Note 9)	
100V	4.3mΩ @ V _{GS} = 10V	100A	

Features

- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low RDS(ON)—Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable. and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Description

This new generation n-channel enhancement mode MOSFET is designed to minimize RDS(ON) yet maintain superior switching performance. This device is ideal for use in notebook battery power management and load switches.

POWERDI5060-8 (Standard)

Applications

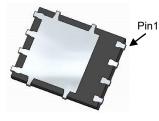
- Motor control
- DC-DC converters
- Power management

Mechanical Data

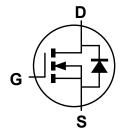
- Package: POWERDI®5060-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (63)
- Weight: 0.097 grams (Approximate)



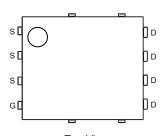




Bottom View



Internal Schematic



Top View Pin Configuration

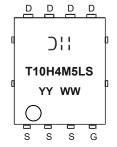
Ordering Information (Note 4)

Orderable Part Number	Daakaga	Packing		
Orderable Part Number	Package	Qty.	Carrier	
DMTH10H4M5LPS-13	POWERDI5060-8 (Standard)	2500	Tape & Reel	

Notes:

- 1, EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant, All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



⊃¡; = Manufacturer's Marking T10H4M5LS = Product Type Marking Code YYWW = Date Code Marking YY or YY = Last Two Digits of Year (ex: 25 = 2025) WW or WW= Week Code (01 to 53)

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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	100	V		
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current, V _{GS} = 10V (Note 5)	Steady State	T _A = +25°C T _A = +100°C	lο	20 14	Α
Continuous Drain Current, $V_{GS} = 10V$ (Note 6) Steady State $T_C = +25^{\circ}C$ $T_C = +100^{\circ}C$ (Note 9)		Ι _D	100 100	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	lрм	400	Α		
Pulsed Body Diode Forward Current (10µs Pulse, T _C =+25°	I _{SM}	400	Α		
Maximum Continuous Body Diode Forward Current (Note 6	Is	100	Α		
Avalanche Current (Note 7) L=0.3mH	las	40	Α		
Avalanche Energy (Note 7) L=0.3mH	E _{AS}	240	mJ		

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T _A = +25°C	PD	2.7	W
Thermal Resistance, Junction to Ambient (Note 5)	Rөja	54	°C/W	
Total Power Dissipation (Note 6) $T_C = +25^{\circ}C$		PD	136	W
Thermal Resistance, Junction to Case (Note 6)		Rejc	1.1	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	100	_	_	V	V _{GS} = 0, I _D = 10mA	
Zero Gate Voltage Drain Current	IDSS	1	_	1	μΑ	V _{DS} = 80V, V _{GS} = 0	
Gate-Source Leakage	I _{GSS}			±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	1.3	_	2.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	Descent		3.5	4.3	mO.	$V_{GS} = 10V, I_D = 30A$	
Static Drain-Source On-Resistance	Rds(on)	1	4.7	6.2	mΩ	V _{GS} = 4.5V, I _D = 20A	
Diode Forward Voltage	V _{SD}	_	_	1.2	V	V _{GS} = 0, I _S = 30A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	4843	_		V _{DS} = 50V, V _{GS} = 0 f = 1MHz	
Output Capacitance	Coss		1302	_	pF		
Reverse Transfer Capacitance	Crss	_	25.5	_		I - IMITZ	
Gate Resistance	R _G		2.1		Ω	$V_{DS} = 0$, $V_{GS} = 0$, $f = 1MHz$	
Total Gate Charge	QG	_	80			501/ 1 204	
Gate-Source Charge	Qgs	_	14		nC	$V_{DD} = 50V, I_D = 30A,$ $V_{GS} = 10V$	
Gate-Drain Charge	Q_{GD}		18	_			
Turn-On Delay Time	t _D (ON)	_	9	_			
Turn-On Rise Time	t _R		26	_	no	V _{DD} = 50V, V _{GS} = 10V,	
Turn-Off Delay Time	tD(OFF)	_	76	_	ns	$I_D = 30A$, $R_G = 4.7\Omega$, $R_L = 1.1\Omega$	
Turn-Off Fall Time	t _F		50	_			
Reverse-Recovery Time	trr		63		ns	L = 22 EA di/dt = 100A/vs	
Reverse-Recovery Charge	QRR	_	133	_	nC I _F = 22.5A, di/dt = 100A/μs		

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

6. Thermal resistance from junction to soldering point (on the exposed drain pad).

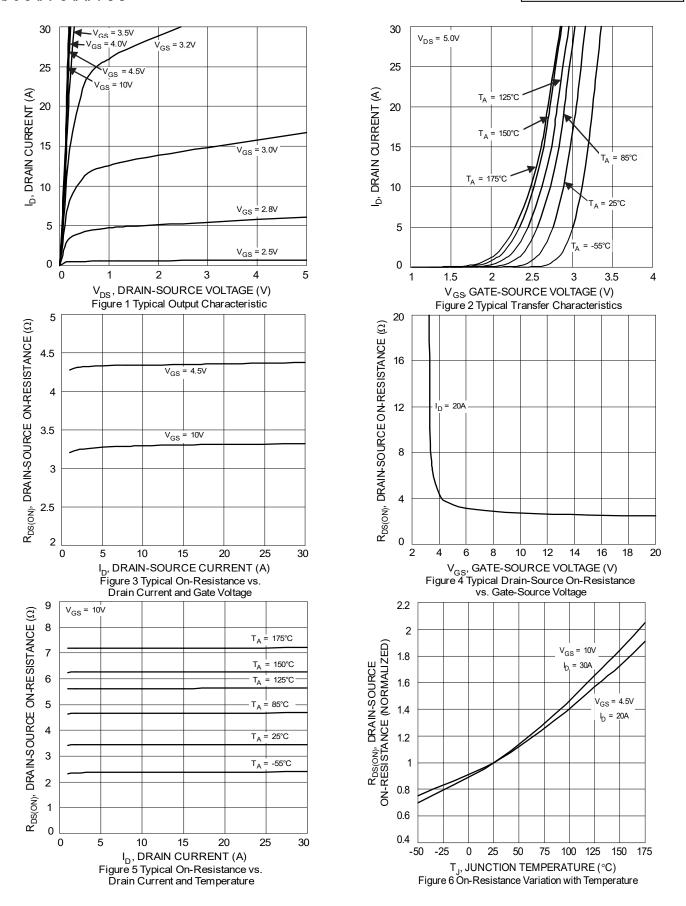
^{7.} Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to product testing.

^{9.} Package limited.

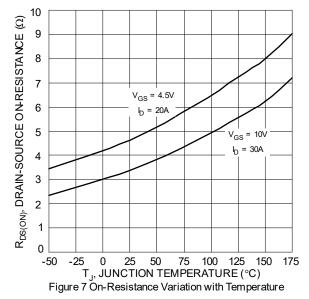


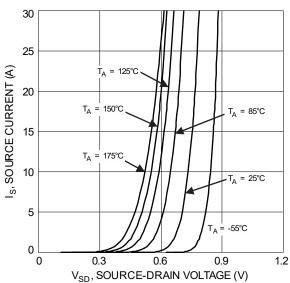


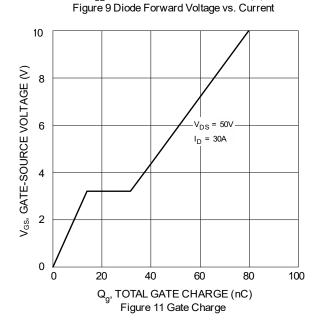












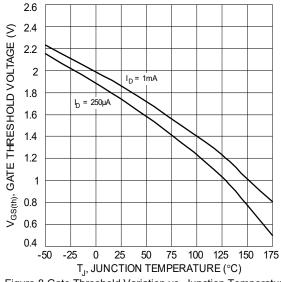
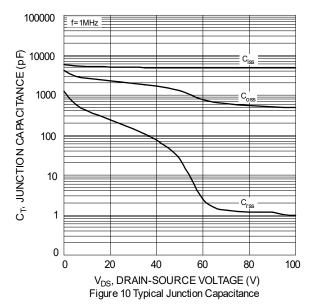
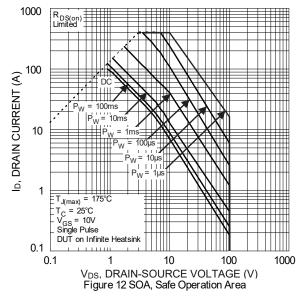
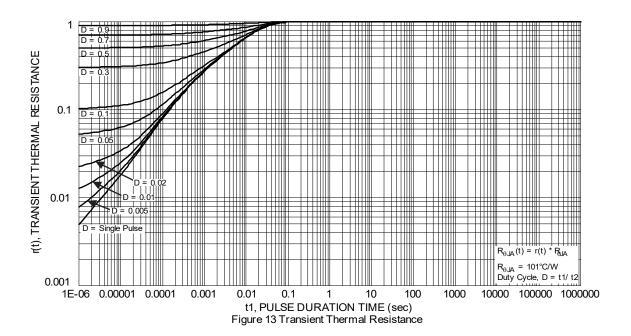


Figure 8 Gate Threshold Variation vs. Junction Temperature







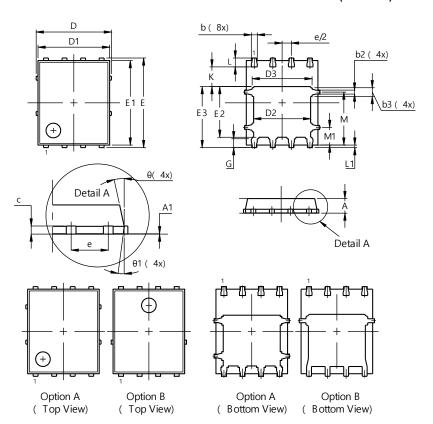




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

POWERDI5060-8 (Standard)

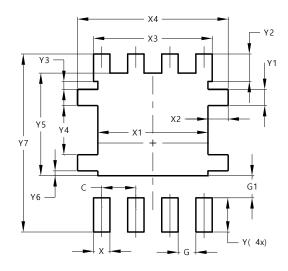


POWERDI5060-8 (Standard)					
Dim	Min	Max	Тур		
Α	0.90	1.20			
A1	0.00	0.05	-		
b	0.33	0.51			
b2	0.200	0.350	-		
b3	0.40	0.80	0.60		
С	0.230	0.354			
D (Option A)	5.	15 BSC			
D (Option B)		30 BSC			
D1	4.70	5.40			
D2	3.70	4.25			
D3	3.90 4.70				
Е	6.15 BSC				
E1	5.60	6.06			
E2	3.28	3.92			
E3	3.99 4.39				
е	1.	27 BSC			
G	0.40	0.71			
K	0.51	1.45			
L	0.38	0.71			
L1	0.100	0.200			
М	3.235	4.035			
M1	1.00	1.40	1.21		
θ	8°	12°			
61 6° 8° 7					
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

POWERDI5060-8 (Standard)



Dimensions	Value (in mm)			
С	1.270			
G	0.660			
G1	0.820			
Х	0.610			
X1	4.300			
X2	0.755			
Х3	4.420			
X4	5.610			
Υ	1.270			
Y1	0.600			
Y2	1.020			
Y3	0.295			
Y4	1.825			
Y5	4.100			
Y6	0.180			
Y7	6.610			



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